EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L5	215	(varnish or paint or gloss or finish) near5 (halogen)	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/04/10 08:07
L6	57149	((Curable or fixable or cure$1 or curing or fix$3) near5 (film$1 or layer$1 or strat$2 or coat$1 or coating$1 or lamina or tier$1 or sheet$1)) with (polymer$1 or plastic$1 or resin$1)	FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/04/10 08:08
L7	2	l5 and l6	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/04/10 08:23
S1	114753	(Multilayer or multi-layer or ((many or multiple or two or plural or multi$1 or two) near3 ((monolayer$1 or mono $1layer$1) or strat$2 or level$1))) with (circuit$2 or chip$1 or microchip or micro $1chip or microcircuit or microprocessor $1 or processor$1 or semiconductor$1 or semi$1conductor$1)	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/03/31 11:13
S2	42650	(Multilayer or multi-layer or ((many or multiple or two or plural or multi$1 or two) near3 ((monolayer$1 or mono $1layer$1) or strat$2 or level$1))) with (circuit$2 or chip$1 or microchip or micro $1chip or microcircuit or microprocessor $1 or processor$1 or semiconductor$1 or semi$1conductor$1)	FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/03/31 11:15
S4	54836	(Coordinate$1 or coordinating or complex or complex$3 or chelate$1 or chelat$3) near5 metal$1	FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/03/31 11:16
S7	39991	(hydrophilic or hydrophiliz$3 or hydrophilic$3 or hydrophilicat$3) near5 (film$1 or layer$1 or strat$2 or coat$1 or coating$1 or lamina or tier$1 or sheet$1 or surface$1)	FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/03/31 11:17
S10	19	((ethylenediaminetetraacetic or edta or C10H16N2O8 or "C.sub.10.H.sub.16.N. sub.2.O.sub.8") with (copper or cu)) with (circuit or conductor or conductive)	FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/03/31 11:18
S20	56431	(hydrophilic or hydrophiliz$3 or hydrophilic$3 or hydrophilicat$3 or water $1soluble or water$1miscible) near5 (film $1 or layer$1 or strat$2 or coat$1 or coating$1 or lamina or tier$1 or sheet$1 or surface$1)	FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/03/31 11:24

S21	81952	(hydrophilic or hydrophiliz$3 or hydrophilic$3 or hydrophilicat$3 or water$1soluble or water$1miscible or potassium permanganate or kmno4 or "KMNO.sub.4") with (film$1 or layer$1 or strat$2 or coat$1 or coating$1 or lamina$4 or tier$1 or sheet$1 or surface$1)	FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/03/31 11:26
S22	328	S4 and S7 and S21	FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/03/31 11:27
S23	178	S4 same S7 same S21	FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/03/31 11:27
S24	0	S23 and S10	FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/03/31 11:27
S25	0	S22 and S1	FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/03/31 11:32
S26	0	S10 and S1	FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/03/31 11:32
S27	6875359	(circuit$2 or chip$1 or microchip or micro$1chip or microcircuit or microprocessor$1 or processor$1 or semiconductor$1 or semi$1conductor$1)	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/03/31 11:33
S28	19	S22 and S27	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/03/31 11:34
S29	8	S27 and S23	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/03/31 11:34
S30	18	S27 and S10	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/03/31 11:35
S32	21	((ethylenediaminetetraacetic or (ethylenediamine near2 (tetraacetic or tetra-acetic or tetra$1acetic)) or edta or C10H16N2O8 or "C.sub.10.H.sub.16.N.sub.2.O.sub.8") with (copper or cu)) with (circuit or conductor or conductive)	FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/03/31 11:42
S33	85	((ethylenediaminetetraacetic or edta or C10H16N2O8 or "C.sub.10.H.sub.16.N.sub.2.O.sub.8") with (copper or cu)) with (circuit or conductor or conductive or (electroless near3 plat$3))	FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/03/31 11:43

S34	31	S33 and S27	FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/03/31 11:54
S35	121385	(Multilayer or multi-layer or ((several or many or multiple or two or plural or multi$1 or two) near3 ((monolayer$1 or mono$1layer$1) or strat$2 or level$1 or lamina$5))) with (circuit$2 or chip$1 or microchip or micro$1chip or microcircuit or microprocessor$1 or processor$1 or semiconductor$1 or semi$1conductor$1)	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/03/31 12:09
S38	2	("0175824").PN.	US-PGPUB; USPAT; USOCR	OR	OFF	2008/03/31 13:02
S39	57100	((Curable or fixable or cure$1 or curing or fix$3) near5 (film$1 or layer$1 or strat$2 or coat$1 or coating$1 or lamina or tier$1 or sheet$1)) with (polymer$1 or plastic$1 or resin$1)	FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/03/31 13:27
S40	5343	S39 and S27	FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/03/31 13:29
S41	20	S39 and S27 and S4	FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/03/31 13:30
S45	73	wakizaka, yasuhiro.inv.	FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/03/31 13:37
S47	1	wakizawa, yasuhiro.inv.	US-PGPUB; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/03/31 13:39
S48	2	S45 and S4	FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/03/31 13:51
S49	0	S4 andl27	FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/03/31 13:56
S50	3274	S4 and S27	FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/03/31 13:56
S51	60	infiltrated layer	FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/03/31 14:12
S52	545	infiltrated near5 layer	FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/03/31 14:13

S55	29418	(nitrogen or N) near5 (heterocyclic or imidazole$1 or pyrazole$1 or triazole$1 or triazine$1)	FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/03/31 14:17
S57	926	S4 and S55	FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/03/31 14:18
S58	48	S57 and S27	FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/03/31 14:18
S59	960	S55 and S27	FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/03/31 14:21
S60	11	S55 and S27 and S39	FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/03/31 14:22
S61	11	S27 and S55 and smooth	FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/03/31 14:32
S62	1	S33 and S55	FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/03/31 16:56
S63	200280	(epoxy or maleimide or methacrylic or meth$1acrylic or (diallyl near2 phthalate) or (alicyclic near2 olefin) or triazine or (aromatic near2 polyether) or benzocyclobutene or (cyanate near2 ester) or (liquid near2 crystal) or polyimide$1) near3 (resin$1 or plastic$1 or polymer$1)	FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/03/31 17:42
S64	8712	S63 and S39	FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/03/31 17:42
S65	62	S63 and S39 and S4	FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/03/31 17:44
S66	1474	S63 and S39 and S27	FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/03/31 17:44
S67	161	S63 and S39 and S1	FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/03/31 17:44

S68	202698	(epoxy or maleimide or methacrylic or meth$1acrylic or (diallyl near2 phthalate) or (alicyclic near2 olefin) or triazine or (aromatic near2 polyether) or benzocyclobutene or (cyanate near2 ester) or (liquid near2 crystal) or polyimide$1 or norbornene) near3 (resin $1 or plastic$1 or polymer$1)	FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/03/31 17:49
S69	8754	S68 and S39	FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/03/31 17:50
S70	62	S68 and S39 and S4	FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/03/31 17:50
S71	161	S68 and S39 and S1	FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/03/31 17:51
S72	1476	S68 and S39 and S27	FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/03/31 17:51
S73	73	S69 and norbornene	FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/03/31 17:52
S74	0	S71 and norbornene	FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/03/31 17:52
S75	36	S1 and norbornene	FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/03/31 17:53
S76	235	S4 and norbornene	FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/03/31 17:54
S78	0	S39 and S33	FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/03/31 18:20
S79	82	S63 and edta	FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/03/31 18:20
S80	13	S63 and (edta with (copper or cu))	FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/03/31 18:21
S81	52290	(hydrophilic or hydrophiliz$3 or hydrophilic$3 or hydrophilicat$3 or potassium permanganate or kmno4 or "KMNO.sub.4") with (film$1 or layer$1 or strat$2 or coat$1 or coating$1 or lamina or tier$1 or sheet$1 or surface $1)	FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/04/07 14:54

S82	666	(hydrophilic or hydrophiliz$3 or hydrophilic$3 or hydrophilicat$3 or potassium permanganate or kmno4 or "KMNO.sub.4") with (((alkali or sodium) near3 hydroxide) or NaOH)	FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/04/07 14:56
S83	42686	(Multilayer or multi-layer or ((many or multiple or two or plural or multi$1 or two) near3 ((monolayer$1 or mono$1layer$1) or strat$2 or level$1))) with (circuit$2 or chip$1 or microchip or micro$1chip or microcircuit or microprocessor$1 or processor$1 or semiconductor$1 or semi$1conductor$1)	FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/04/07 14:57
S86	6884795	(circuit$2 or chip$1 or microchip or micro$1chip or microcircuit or microprocessor$1 or processor$1 or semiconductor$1 or semi$1conductor$1)	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/04/07 14:59
S87	34	S82 and S86	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/04/07 14:59
S88	595	(potassium permanganate or kmno4 or "KMNO.sub.4") with (film$1 or layer$1 or strat$2 or coat$1 or coating$1 or lamina or tier$1 or sheet$1 or surface$1)	FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/04/07 15:01
S89	296	(potassium permanganate or kmno4 or "KMNO.sub.4") with (((alkali or sodium) near3 hydroxide) or NaOH)	FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/04/07 15:01
S90	26	S86 and S89	FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/04/07 15:02
S91	1	("7056424").PN.	US-PGPUB; USPAT; USOCR	OR	OFF	2008/04/07 15:08
S92	1	("5104687").PN.	US-PGPUB; USPAT; USOCR	OR	OFF	2008/04/07 15:30
S93	54900	(Coordinate$1 or coordinating or complex or complex$3 or chelate$1 or chelat$3) near5 metal$1	FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/04/07 15:51
S94	29445	(nitrogen or N) near5 (heterocyclic or imidazole$1 or pyrazole$1 or triazole$1 or triazine$1)	FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/04/07 15:51
S95	927	S93 and S94	FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/04/07 15:51
S96	40022	(hydrophilic or hydrophiliz$3 or hydrophilic$3 or hydrophilicat$3) near5 (film$1 or layer$1 or strat$2 or coat$1 or coating$1 or lamina or tier$1 or sheet$1 or surface$1)	FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/04/07 15:54

S97	5	S96 and S93 and S94	FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/04/07 15:54
S98	328	S96 and S93	FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/04/07 15:55
S99	57149	(((Curable or fixable or cure$1 or curing or fix$3) near5 (film$1 or layer$1 or strat$2 or coat$1 or coating$1 or lamina or tier$1 or sheet$1)) with (polymer$1 or plastic$1 or resin$1)	FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/04/07 15:56
S100	5	S96 and S93 and S99	FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/04/07 15:56
S101	9897	S99 and laminat$3	FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/04/07 16:15
S102	1148	S99 and S86 and laminat$3	FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/04/07 16:16
S103	201	S99 and S86 and laminat$3 and S83	FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/04/07 16:17
S104	139	S99 and S86 and laminat$3 and S83 and (insulat$3 or dielectric)	FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/04/07 16:18
S106	119	S99 and S86 and (insulat$3 or dielectric) and (varnish or glaze or paint)	FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/04/07 16:36
S109	1	S99 and S86 and (insulat$3 or dielectric) and ((varnish or glaze or paint) near5 ((inner or inside) near3 (layer$1 or strat$2 or level$1 or lamina$5)))	FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/04/07 16:41
S110	19835	(electroless or non adj electrolytic or non-electrolytic) near3 (plate or plating)	FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/04/09 07:37
S111	121645	(Multilayer or multi-layer or ((several or many or multiple or two or plural or multi$1 or two) near3 ((monolayer$1 or mono$1layer$1) or strat$2 or level$1 or lamina$5))) with (circuit$2 or chip$1 or microchip or micro$1chip or microcircuit or microprocessor$1 or processor$1 or semiconductor$1 or semi$1conductor$1)	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/04/09 07:39
S112	57149	(((Curable or fixable or cure$1 or curing or fix$3) near5 (film$1 or layer$1 or strat$2 or coat$1 or coating$1 or lamina or tier$1 or sheet$1)) with (polymer$1 or plastic$1 or resin$1)	FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/04/09 07:39

S113	15	S111 and S110 and S112	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/04/09 07:39
S114	0	S111 and S110 and S112 and smooth	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/04/09 07:41
S115	7	S111 and S110 and smooth	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/04/09 07:49
S116	0	10-022634	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/04/09 07:55
S117	11	"10022634"	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/04/09 07:55
S118	3	S111 and ((Coordinate$1 or coordinating or complex or complex$3 or chelate$1 or chelat$3) near5 metal$1) and smooth	FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/04/09 08:11
S119	417	S111 and ((Coordinate$1 or coordinating or complex or complex$3 or chelate$1 or chelat$3) near5 metal$1) and smooth	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/04/09 08:12
S120	29445	(nitrogen or N) near5 (heterocyclic or imidazole$1 or pyrazole$1 or triazole$1 or triazine$1)	FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/04/09 08:21
S121	1	S111 and S120 and smooth	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/04/09 08:21
S122	1	S110 and S111 and S112 and S120	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/04/09 08:24
S123	1	"63211796"	JPO; DERWENT; IBM_TDB	ADJ	ON	2008/04/09 08:43
S128	232882	(resist$1 or mask$1 or masking$1) near5 (pattern$1 or patterning$1 or template$1 or design$1)	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/04/09 10:05

S129	775	S128 and S110	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/04/09 10:06
S130	115000	(Multilayer or multi-layer or ((many or multiple or two or plural or multi$1 or two) near3 ((monolayer$1 or mono$1layer$1) or strat$2 or level$1))) with (circuit$2 or chip$1 or microchip or micro$1chip or microcircuit or microprocessor$1 or processor$1 or semiconductor$1 or semi$1conductor$1)	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/04/09 10:07
S131	12930	S128 and S130	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/04/09 10:07
S132	164	S131 and (CuCl2 or "CuCl.sub.2" or cupric chloride) and (hydrochloric acid or HCl)	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/04/09 10:09
S133	232882	(resist$1 or mask$1 or masking$1) near5 (pattern$1 or patterning$1 or template$1 or design$1)	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/04/09 10:22
S134	115000	(Multilayer or multi-layer or ((many or multiple or two or plural or multi$1 or two) near3 ((monolayer$1 or mono$1layer$1) or strat$2 or level$1))) with (circuit$2 or chip$1 or microchip or micro$1chip or microcircuit or microprocessor$1 or processor$1 or semiconductor$1 or semi$1conductor$1)	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/04/09 10:22
S135	12930	S133 and S134	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/04/09 10:22
S136	164	S135 and (CuCl2 or "CuCl.sub.2" or cupric chloride) and (hydrochloric acid or HCl)	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/04/09 10:22
S144	4156887	(heat or (high near2 temperature) or oven or anneal$3)	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/04/09 10:37
S145	18891	S133 same S144	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/04/09 10:39

S146	1416	(CuCl2 or "CuCl.sub.2" or cupric chloride) with (hydrochloric acid or HCl)	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/04/09 10:40
S147	12	S145 same S146	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/04/09 10:40
S148	36718	S134 and S144	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/04/09 10:42
S149	94	S148 and S146	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/04/09 10:43
S150	115000	(Multilayer or multi-layer or ((many or multiple or two or plural or multi$1 or two) near3 ((monolayer$1 or mono$1layer$1) or strat$2 or level$1))) with (circuit$2 or chip$1 or microchip or micro$1chip or microcircuit or microprocessor$1 or processor$1 or semiconductor$1 or semi$1conductor$1)	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/04/09 11:08
S151	19905	S150 and ((two near3 side$1) or (double near3 side$1) or (both near3 side$1))	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/04/09 11:08
S152	79	S151 and S146	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/04/09 11:09
S154	10371	S151 and ((CuCl2 or "CuCl.sub.2" or cupric chloride) with (hydrochloric acid or HCl) or etch$3)	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/04/09 11:11
S155	7462	S154 and S144	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/04/09 11:12
S156	382	S154 and S144 and "427".clas.	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/04/09 11:15
S157	262572	(resist$1 or photo$1resist or mask$1 or masking$1) near5 (pattern$1 or patterning$1 or template$1 or design$1)	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/04/09 11:17

S158	41	S133 same S146	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/04/09 11:18
S159	12	S133 same S146 same S144	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/04/09 11:18
S160	2	"7323093"	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/04/09 11:36
S161	85643	anneal$3 and etch$3	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/04/09 11:37
S162	51	S161 and S146	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/04/09 11:38
S163	155653	"427".clas.	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/04/09 12:05
S164	374759	"427".clas. or "216".clas. or "438".clas.	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/04/09 12:06
S165	121645	(Multilayer or multi-layer or ((several or many or multiple or two or plural or multi $1 or two) near3 ((monolayer$1 or mono $1layer$1) or strat$2 or level$1 or lamina $5))) with (circuit$2 or chip$1 or microchip or micro$1chip or microcircuit or microprocessor$1 or processor$1 or semiconductor$1 or semi$1conductor$1)	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/04/09 12:07
S166	15412	S164 and S165	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/04/09 12:07
S170	39	wakizaka.inv. and multilayer circuit	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/04/09 15:03
S171	8	wakizaka.inv. and multilayer circuit	US-PGPUB	ADJ	ON	2008/04/09 15:07
S172	2	wakizawa.inv. and multilayer circuit	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/04/09 15:11

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